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Details

Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	24MHz
Connectivity	SPI, UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89s8253-24pi

3.5 PWRGND

Ground for the 42-PDIP which connects only the I/O Pad Drivers. PWRGND and GND are weakly connected through the common silicon substrate, but not through any metal links. The application board **must** connect both GND and PWRGND to the board ground.

3.6 Port 0

Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink six TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.**

3.7 Port 1

Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source six TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the weak internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL} , 150 μ A typical) because of the weak internal pull-ups.

Some Port 1 pins provide additional functions. P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively. Furthermore, P1.4, P1.5, P1.6, and P1.7 can be configured as the SPI slave port select, data input/output and shift clock input/output pins as shown in the following table.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.4	\overline{SS} (Slave port select input)
P1.5	MOSI (Master data output, slave data input pin for SPI channel)
P1.6	MISO (Master data input, slave data output pin for SPI channel)
P1.7	SCK (Master clock output, slave clock input pin for SPI channel)

Port 1 also receives the low-order address bytes during Flash programming and verification.

3.8 Port 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source six TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the weak internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL} , 150 μ A typical) because of the weak internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

In addition, during EEPROM programming, an attempted read from the EEPROM will fetch the byte being written with the MSB complemented. Once the write cycle is completed, true data are valid at all bit locations.

6.1 Memory Control Register

The EECON register contains control bits for the 2K bytes of on-chip data EEPROM. It also contains the control bit for the dual data pointer.

Table 6-1. EECON – Data EEPROM Control Register

EECON Address = 96H

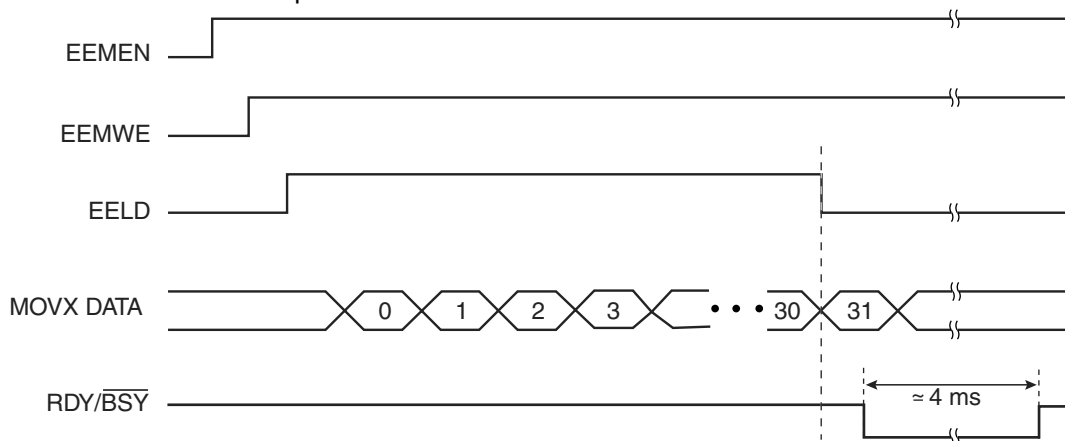
Reset Value = XX00 0011B

Not Bit Addressable

Bit	–	–	EELD	EEMWE	EEMEN	DPS	RDY/BSY	WRTINH
	7	6	5	4	3	2	1	0

Symbol	Function
EELD	EEPROM data memory load enable bit. Used to implement Page Mode Write. A MOVX instruction writing into the data EEPROM will not initiate the programming cycle if this bit is set, rather it will just load data into the volatile data buffer of the data EEPROM memory. Before the last MOVX, reset this bit and the data EEPROM will program all the bytes previously loaded on the same page of the address given by the last MOVX instruction.
EEMWE	EEPROM data memory write enable bit. Set this bit to 1 before initiating byte write to on-chip EEPROM with the MOVX instruction. User software should set this bit to 0 after EEPROM write is completed.
EEMEN	Internal EEPROM access enable. When EEMEN = 1, the MOVX instruction with DPTR will access on-chip EEPROM instead of external data memory if the address used is less than 2K. When EEMEN = 0 or the address used is $\geq 2K$, MOVX with DPTR accesses external data memory.
DPS	Data pointer register select. DPS = 0 selects the first bank of data pointer register, DP0, and DPS = 1 selects the second bank, DP1.
RDY/BSY	RDY/BSY (Ready/Busy) flag for the data EEPROM memory. This is a read-only bit which is cleared by hardware during the programming cycle of the on-chip EEPROM. It is also set by hardware when the programming is completed. Note that RDY/BSY will be cleared long after the completion of the MOVX instruction which has initiated the programming cycle.
WRTINH	WRTINH (Write Inhibit) is a READ-ONLY bit which is cleared by hardware when V_{cc} is too low for the programming cycle of the on-chip EEPROM to be executed. When this bit is cleared, an ongoing programming cycle will be aborted or a new programming cycle will not start.

Figure 6-1. Data EEPROM Write Sequence



8.1 Watchdog Control Register

The WDTCON register contains control bits for the Watchdog Timer (shown in Table 8-2).

Table 8-2. WDTCON – Watchdog Control Register

WDTCON Address = A7H

Reset Value = 0000 0000B

Not Bit Addressable

	PS2	PS1	PS0	WDIDLE	DISRTO	HWDT	WSWRST	WDTEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
PS2 PS1 PS0	Prescaler bits for the watchdog timer (WDT). When all three bits are cleared to 0, the watchdog timer has a nominal period of 16K machine cycles, (i.e. 16 ms at a XTAL frequency of 12 MHz in normal mode or 6 MHz in x2 mode). When all three bits are set to 1, the nominal period is 2048K machine cycles, (i.e. 2048 ms at 12 MHz clock frequency in normal mode or 6 MHz in x2 mode).
WDIDLE	Enable/disable the Watchdog Timer in IDLE mode. When WDIDLE = 0, WDT continues to count in IDLE mode. When WDIDLE = 1, WDT freezes while the device is in IDLE mode.
DISRTO	Enable/disable the WDT-driven Reset Out (WDT drives the RST pin). When DISRTO = 0, the RST pin is driven high after WDT times out and the entire board is reset. When DISRTO = 1, the RST pin remains only as an input and the WDT resets only the microcontroller internally after WDT times out.
HWDT	Hardware mode select for the WDT. When HWDT = 0, the WDT can be turned on/off by simply setting or clearing WDTEN in the same register (this is the software mode for WDT). When HWDT = 1, the WDT has to be set by writing the sequence 1EH/E1H to the WDTRST register (with address 0A6H) and after being set in this way, WDT cannot be turned off except by reset, warm or cold (this is the hardware mode for WDT). To prevent the hardware WDT from resetting the entire device, the same sequence 1EH/E1H must be written to the same WDTRST SFR before the timeout interval.
WSWRST	Watchdog software reset bit. If HWDT = 0 (i.e. WDT is in software controlled mode), when set by software, this bit resets WDT. After being set by software, WSWRST is reset by hardware during the next machine cycle. If HWDT = 1, this bit has no effect, and if set by software, it will not be cleared by hardware.
WDTEN	Watchdog software enable bit. When HWDT = 0 (i.e. WDT is in software-controlled mode), this bit enables WDT when set to 1 and disables WDT when cleared to 0 (it does not reset WDT in this case, but just freezes the existing counter state). If HWDT = 1, this bit is READ-ONLY and reflects the status of the WDT (whether it is running or not).

Figure 8-1. Software Mode – Watchdog Timer Sequence

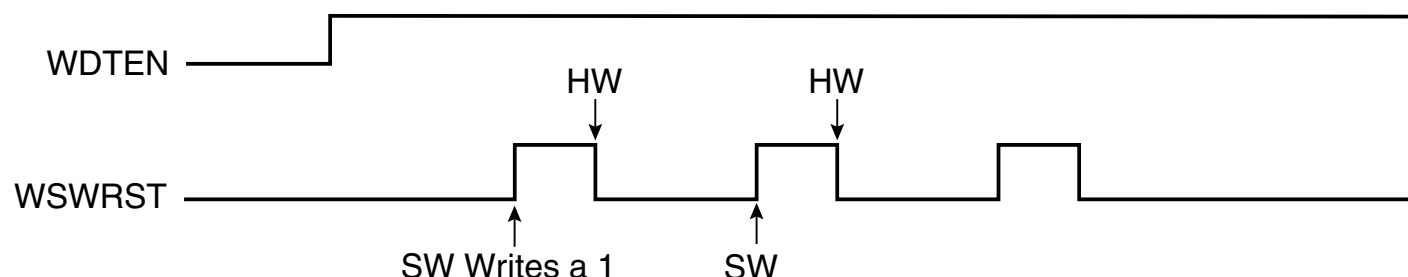


Table 10-2. T2CON – Timer/Counter 2 Control Register

T2CON Address = 0C8H

Reset Value = 0000 0000B

Bit Addressable

	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/ $\overline{T2}$	CP/ $\overline{RL2}$
Bit	7	6	5	4	3	2	1	0

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in serial port Modes 1 and 3. RCLK = 0 causes Timer 1 overflows to be used for the receive clock.
TCLK	Transmit clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in serial port Modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	Timer 2 external enable. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/Stop control for Timer 2. TR2 = 1 starts the timer.
C/ $\overline{T2}$	Timer or counter select for Timer 2. C/ $\overline{T2}$ = 0 for timer function. C/ $\overline{T2}$ = 1 for external event counter (falling edge triggered).
CP/ $\overline{RL2}$	Capture/Reload select. CP/ $\overline{RL2}$ = 1 causes captures to occur on negative transitions at T2EX if EXEN2 = 1. CP/ $\overline{RL2}$ = 0 causes automatic reloads to occur when Timer 2 overflows or negative transitions occur at T2EX when EXEN2 = 1. When either RCLK or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

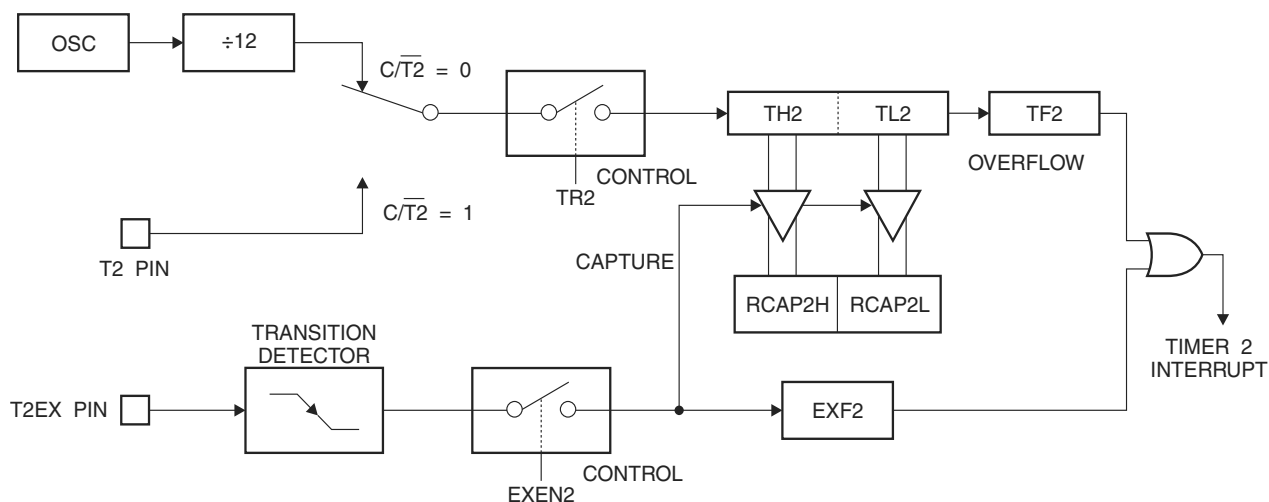
10.1 Timer 2 Registers

Control and status bits are contained in registers T2CON (see Table 10-2) and T2MOD (see Table 10-3) for Timer 2. The register pair (RCAP2H, RCAP2L) are the Capture/Reload registers for Timer 2 in 16-bit capture mode or 16-bit auto-reload mode.

10.2 Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 10-1.

Figure 10-1. Timer 2 in Capture Mode



10.3 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 10-3). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Table 10-3. T2MOD – Timer 2 Mode Control Register

T2MOD Address = 0C9H

Reset Value = XXXX XX00B

Not Bit Addressable

	–	–	–	–	–	–	T2OE	DCEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
–	Not implemented, reserved for future use.
T2OE	Timer 2 Output Enable bit.
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter.

Figure 10-2 shows Timer 2 automatically counting up when DCEN = 0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in RCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 10-3. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit

value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.

A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.

Figure 10-2. Timer 2 in Auto Reload Mode (DCEN = 0)

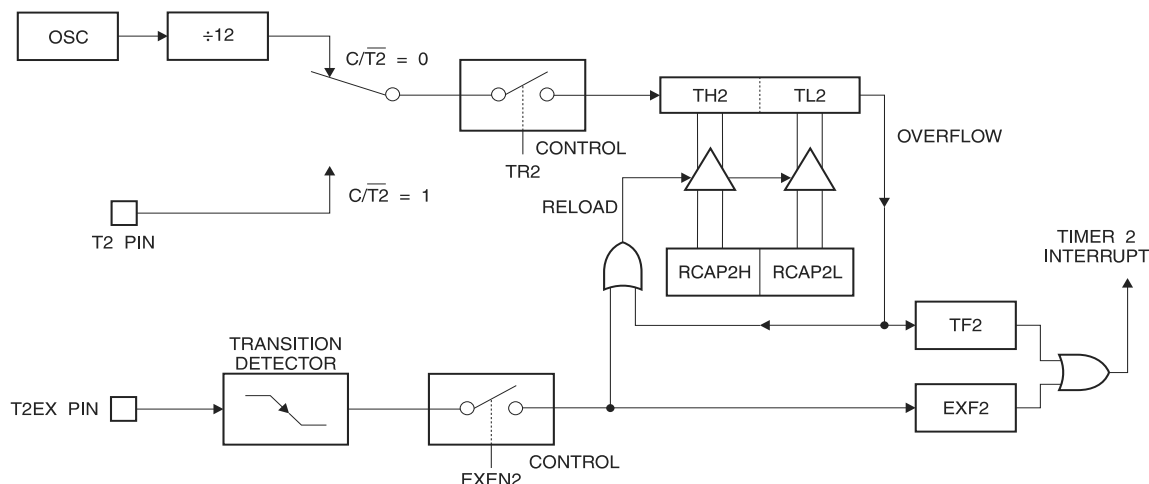
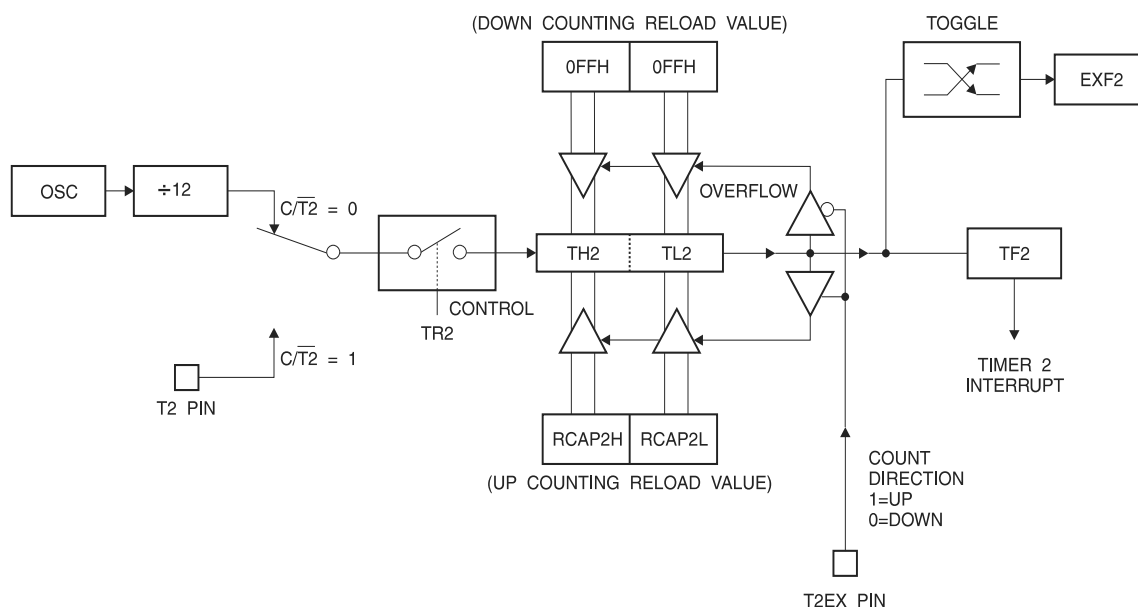


Figure 10-3. Timer 2 Auto Reload Mode (DCEN = 1)



- Notes: 1. SMOD0 is located at PCON.6.
2. f_{osc} = oscillator frequency.

14. Serial Peripheral Interface

The serial peripheral interface (SPI) allows high-speed synchronous data transfer between the AT89S8253 and peripheral devices or between multiple AT89S8253 devices. The AT89S8253 SPI features include the following:

- Full-Duplex, 3-Wire Synchronous Data Transfer
- Master or Slave Operation
- Maximum Bit Frequency = $f/4$ ($f/2$ if in x2 Clock Mode)
- LSB First or MSB First Data Transfer
- Four Programmable Bit Rates in Master Mode
- End of Transmission Interrupt Flag
- Write Collision Flag Protection
- Double-Buffered Receive
- Double-Buffered Transmit (Enhanced Mode only)
- Wakeup from Idle Mode (Slave Mode only)

The interconnection between master and slave CPUs with SPI is shown in Figure 14-1. The four pins in the interface are Master-In/Slave-Out (MISO), Master-Out/Slave-In (MOSI), Shift Clock (SCK), and Slave Select (\overline{SS}). The SCK pin is the clock output in master mode, but is the clock input in slave mode. The MSTR bit in SPCR determines the directions of MISO and MOSI. Also notice that MOSI connects to MOSI and MISO to MISO. In master mode, $\overline{SS}/P1.4$ is ignored and may be used as a general-purpose input or output. In slave mode, \overline{SS} must be driven low to select an individual device as a slave. When \overline{SS} is driven high, the slave's SPI port is deactivated and the MOSI/P1.5 pin can be used as a general-purpose input.

Figure 14-1. SPI Master-Slave Interconnection

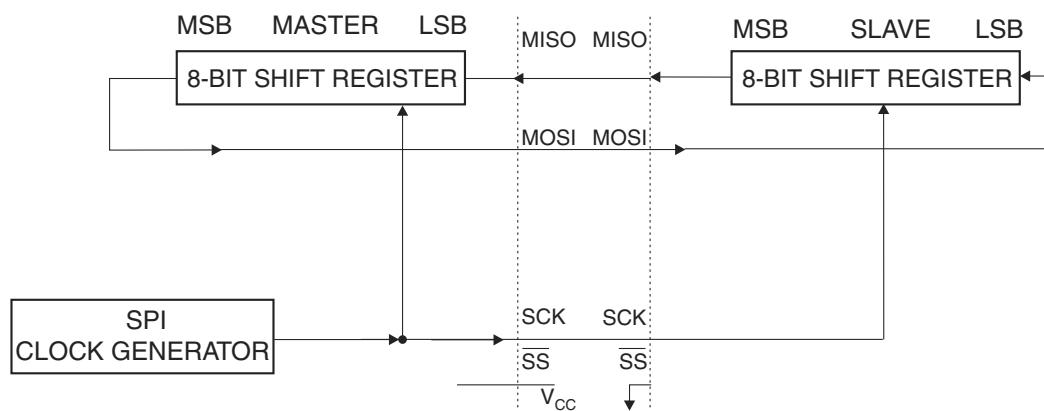


Table 14-1. SPCR – SPI Control Register

SPCR Address = D5H

Reset Value = 0000 0100B

Not Bit Addressable

	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0
Bit	7	6	5	4	3	2	1	0

Symbol	Function
SPIE	SPI interrupt enable. This bit, in conjunction with the ES bit in the IE register, enables SPI interrupts: SPIE = 1 and ES = 1 enable SPI interrupts. SPIE = 0 disables SPI interrupts.
SPE	SPI enable. SPI = 1 enables the SPI channel and connects \overline{SS} , MOSI, MISO and SCK to pins P1.4, P1.5, P1.6, and P1.7. SPI = 0 disables the SPI channel.
DORD	Data order. DORD = 1 selects LSB first data transmission. DORD = 0 selects MSB first data transmission.
MSTR	Master/slave select. MSTR = 1 selects Master SPI mode. MSTR = 0 selects slave SPI mode.
CPOL	Clock polarity. When CPOL = 1, SCK is high when idle. When CPOL = 0, SCK of the master device is low when not transmitting. Please refer to figure on SPI clock phase and polarity control.
CPHA	Clock phase. The CPHA bit together with the CPOL bit controls the clock and data relationship between master and slave. Please refer to figure on SPI clock phase and polarity control.
SPR0 SPR1	<p>SPI clock rate select. These two bits control the SCK rate of the device configured as master. SPR1 and SPR0 have no effect on the slave. The relationship between SCK and the oscillator frequency, F_{OSC}, is as follows:</p> <p>SPR1SPR0SCK</p> <p>00f/4 (f/2 in x2 mode)</p> <p>01f/16 (f/8 in x2 mode)</p> <p>10f/64 (f/32 in x2 mode)</p> <p>11f/128 (f/64 in x2 mode)</p>

- Notes:
1. Set up the clock mode before enabling the SPI: set all bits needed in SPCR except the SPE bit, then set SPE.
 2. Enable the master SPI prior to the slave device.
 3. Slave echoes master on next Tx if not loaded with new data.

Table 14-2. SPSR – SPI Status Register

SPSR Address = AAH

Reset Value = 000X XX00B

Not Bit Addressable

	SPIF	WCOL	LDEN	–	–	–	DISSO	ENH
Bit	7	6	5	4	3	2	1	0

Symbol	Function
SPIF	SPI interrupt flag. When a serial transfer is complete, the SPIF bit is set and an interrupt is generated if SPIE = 1 and ES = 1. The SPIF bit is cleared by reading the SPI status register followed by reading/writing the SPI data register.
WCOL	When ENH = 0: Write collision flag. The WCOL bit is set if the SPI data register is written during a data transfer. During data transfer, the result of reading the SPDR register may be incorrect, and writing to it has no effect. The WCOL bit (and the SPIF bit) are cleared by reading the SPI status register followed by reading/writing the SPI data register. When ENH = 1: WCOL works in Enhanced mode as Tx Buffer Full. Writing during WCOL = 1 in enhanced mode will overwrite the waiting data already present in the Tx Buffer. In this mode, WCOL is no longer reset by the SPIF reset but is reset when the write buffer has been unloaded into the serial shift register.
LDEN	Load enable for the Tx buffer in enhanced SPI mode. When ENH is set, it is safe to load the Tx Buffer while LDEN = 1 and WCOL = 0. LDEN is high during bits 0 - 3 and is low during bits 4 - 7 of the SPI serial byte transmission time frame.
DISSO	Disable slave output bit. When set, this bit causes the MISO pin to be tri-stated so more than one slave device can share the same interface with a single master. Normally, the first byte in a transmission could be the slave address and only the selected slave should clear its DISSO bit.
ENH	Enhanced SPI mode select bit. When ENH = 0, SPI is in normal mode, i.e. without write double buffering. When ENH = 1, SPI is in enhanced mode with write double buffering. The Tx buffer shares the same address with the SPDR register.

Table 14-3. SPDR – SPI Data Register

SPDR Address = 86H

Not Bit Addressable

Reset Value = 00H (after cold reset)

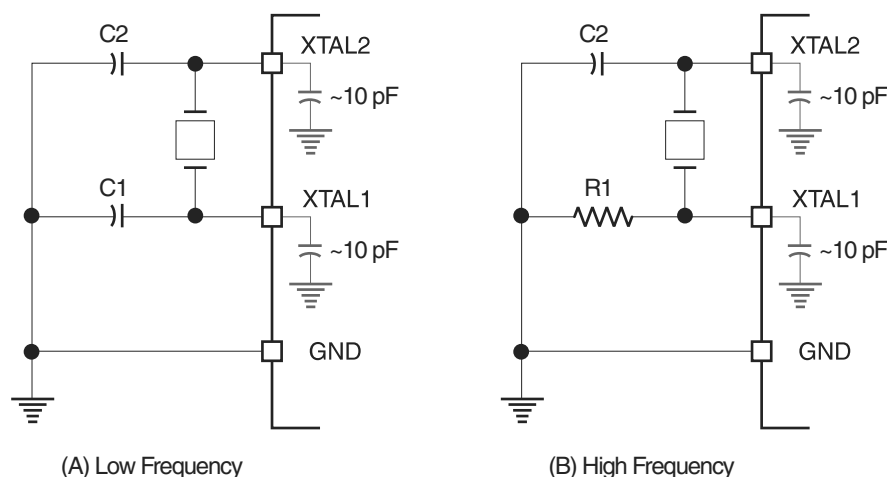
unchanged (after warm reset)

	SPD7	SPD6	SPD5	SPD4	SPD3	SPD2	SPD1	SPD0
Bit	7	6	5	4	3	2	1	0

16. Oscillator Characteristics

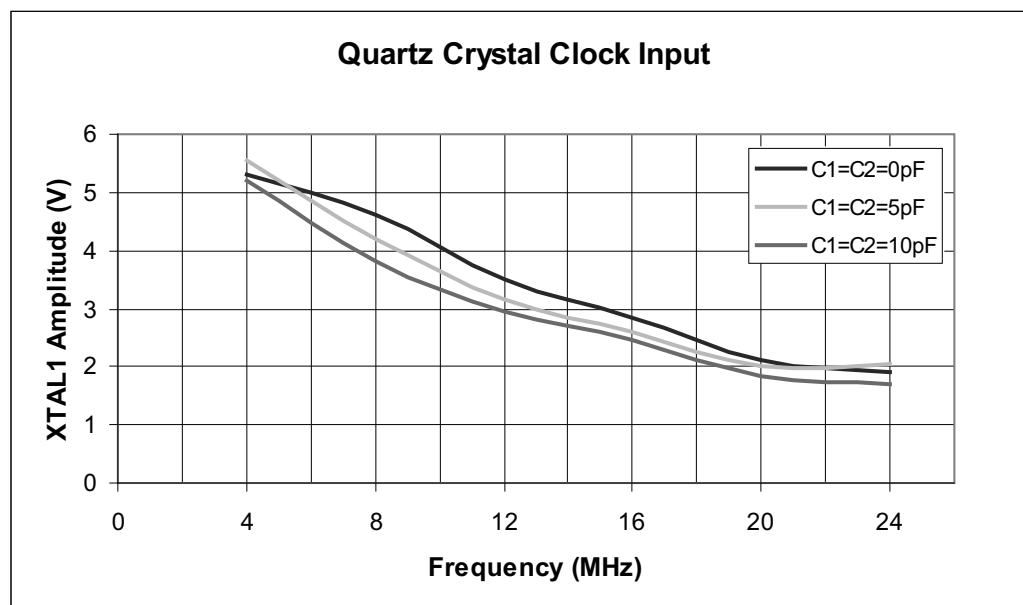
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 16-1 (A) and (B). Either a quartz crystal or ceramic resonator may be used. For frequencies above 16MHz it is recommended that C1 be replaced with R1 for improved startup performance. Note that the internal structure of the devices adds about 10 pF of capacitance to both XTAL1 and XTAL2. The total capacitance on XTAL1 or XTAL2, including the external load capacitor (C1/C2) plus internal device load, board trace and crystal loadings, should not exceed 20 pF. Figure 16-2, 16-3, 16-4 and 16-5 illustrate the relationship between clock loading and the respective resulting clock amplitudes.

Figure 16-1. Oscillator Connections



Note: C1, C2 = 0–10 pF for Crystals
 = 0–10 pF for Ceramic Resonators
 R1 = 4–5 MΩ

Figure 16-2. Quartz Crystal Clock Source (A)



20. Programming the Flash and EEPROM

Atmel's AT89S8253 Flash microcontroller offers 12K bytes of In-System reprogrammable Flash code memory and 2K bytes of EEPROM data memory.

The AT89S8253 is normally shipped with the on-chip Flash code and EEPROM data memory arrays in the erased state (i.e. contents = FFH) and ready to be programmed. This device supports a parallel programming mode and a serial programming mode. The serial programming mode provides a convenient way to reprogram the AT89S8253 inside the user's system. The parallel programming mode is compatible with conventional third-party Flash or EPROM programmers.

The code and data memory arrays are mapped via separate address spaces in the parallel and serial programming modes: 0000H to 2FFFFH for code memory and 000H to 7FFFH for data memory.

The code and data memory arrays in the AT89S8253 are programmed byte-by-byte or by page in either programming mode. To reprogram any non-blank byte in the parallel or serial mode, the user needs to invoke the Chip Erase operation first to erase both arrays since there is no built-in auto-erase capability.

Parallel Programming Algorithm: To program and verify the AT89S8253 in the parallel programming mode, the following sequence is recommended (see Figure 26-1):

1. Power-up sequence:
 - a. Apply power between V_{CC} and GND pins.
 - b. Set RST pin to "H".
 - c. Apply a 3 MHz to 24 MHz clock to XTAL1 pin and wait for at least 10 ms.
2. Set \overline{PSEN} pin to "L"
 - a. ALE pin to "H"
 - b. \overline{EA} pin to "H" and all other pins to "H".
3. Raise \overline{EA}/VPP to 12V to enable Flash programming, erase or verification. Enable the P3.0 pull-up (10 K Ω typical) for RDY/ \overline{BSY} operation.
4. Apply the appropriate combination of "H" or "L" logic levels to pins P3.3, P3.4, P3.5, P3.6, P3.7 to select one of the programming operations shown in the Flash Programming Modes table.
5. Apply the desired byte address to pins P1.0 to P1.7 and P2.0 to P2.5.
 - a. Apply data to pins P0.0 to P0.7 for write code operation.
6. Pulse ALE/ \overline{PROG} once to load a byte in the code memory array, the data memory array, or the lock bits.
7. Repeat steps 5 and 6, changing the address and data for up to 64 bytes in the code memory page or 32 bytes in the data memory (EEPROM) page. When loading a page with individual bytes, the interval between consecutive byte loads should be no longer than 150 μ s. Otherwise the device internally times out and assumes that the page load sequence is completed, rejecting any further loads before the page programming sequence has finished. This timing restriction also applies to Page Write of the 64-byte User Row.
8. After the last byte of the current page has been loaded, wait for 5 ms or monitor the RDY/ \overline{BUSY} pin until it transitions high. The page write cycle is self-timed and typically takes less than 5 ms.
9. To verify the last byte of the page just programmed, bring pin P3.4 to "L" and read the programmed data at pins P0.0 to P0.7.

25. Flash and EEPROM Parallel Programming Modes

Mode		RST	PSEN	ALE	EA	P3.3	P3.4	P3.5	P3.6	P3.7	Data I/O P0.7:0	Address P2.5:0, P1.7:0
Serial Prog. Modes ⁽¹⁾		H	h	h								
Chip Erase ⁽²⁾		H	L	1.0 μs	12V	H	L	H	L	L	X	X
Page Write ⁽³⁾⁽⁴⁾⁽⁵⁾	12K Code	H	L	1.0 μs	12V	L	H	H	H	H	DI	ADDR
Read	12K Code	H	L	H	12V	L	L	H	H	H	DO	ADDR
Page Write ⁽³⁾⁽⁴⁾⁽⁶⁾	2K Data	H	L	1.0 μs	12V	L	H	L	H	H	DI	ADDR
Read	2K Data	H	L	H	12V	L	L	L	H	H	DO	ADDR
Write Lock Bits ⁽²⁾⁽⁴⁾	Bit - 1	H	L	1.0 μs	12V	H	L	H	H	L	D0 = 0	X
	Bit - 2										D1 = 0	X
	Bit - 3										D2 = 0	X
Read Lock Bits	Bit - 1	H	L	H	12V	H	H	H	L	L	D0	X
	Bit - 2										D1	X
	Bit - 3										D2	X
Page Write ⁽³⁾⁽⁴⁾⁽⁵⁾	User Row	H	L	1.0 μs	12V	H	L	H	H	H	DI	0 - 3FH
Read	User Row	H	L	H	12V	L	L	H	L	H	DO	0 - 3FH
Read	Sig. Row	H	L	H	12V	L	L	H	L	L	DO	0 - 3FH
Write Fuse ⁽²⁾⁽⁴⁾⁽⁷⁾	Fuse1 {	H	L	1.0 μs	12V	L	H	H	L	H	D0 = 0	X
											D0 = 1	X
	Fuse2 {										D1 = 0	X
											D1 = 1	X
	Fuse3 {										D2 = 0	X
											D2 = 1	X
	Fuse4 {										D3 = 0	X
											D3 = 1	X
Read Fuse	SerialPrg (Fuse1)	H	L	H	12V	H	H	H	L	H	D0	X
	x2 Clock (Fuse2)										D1	X
	UsrRow Prg (Fuse3)										D2	X
	Clock Select (Fuse4)										D2	X

- Notes:
1. See detailed timing for Serial Programming Mode.
 2. Internally timed for 8.0 ms.
 3. Internally timed for 8.0 ms. Programming begins 150 μ s (minimum) after the last write pulse.
 4. P3.0 is pulled low during programming to indicate RDY/BSY
 5. 1 to 64 bytes can be programmed at a time per page.
 6. 1 to 32 bytes can be programmed at a time per page.
 7. Fuse Definitions:
Fuse1 (Serial Programming Fuse): This fuse enables/disables the serial programming mode (ISP).
Fuse2 (x2 Mode Selection Fuse): This fuse enables/disables the internal x2 clock mode.

Fuse3 (User Row Access Fuse): This fuse enables/disables writing to the programmable user row.

Fuse4 (Clock Selection Fuse): This fuse selects between an external clock source and a quartz crystal as the clock input.

Programming the Flash/EEPROM Memory (Parallel Mode)

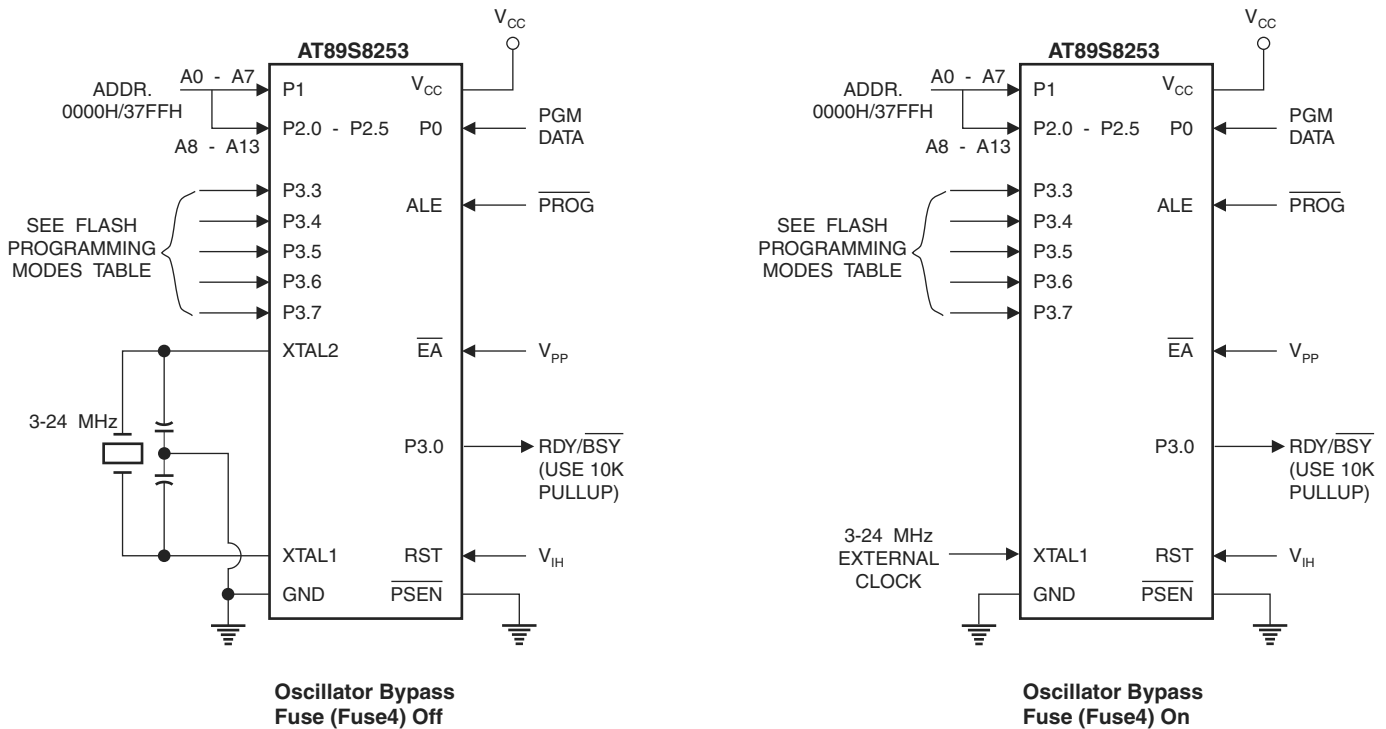


Figure 25-2. Verifying the Flash/EEPROM Memory (Parallel Mode)

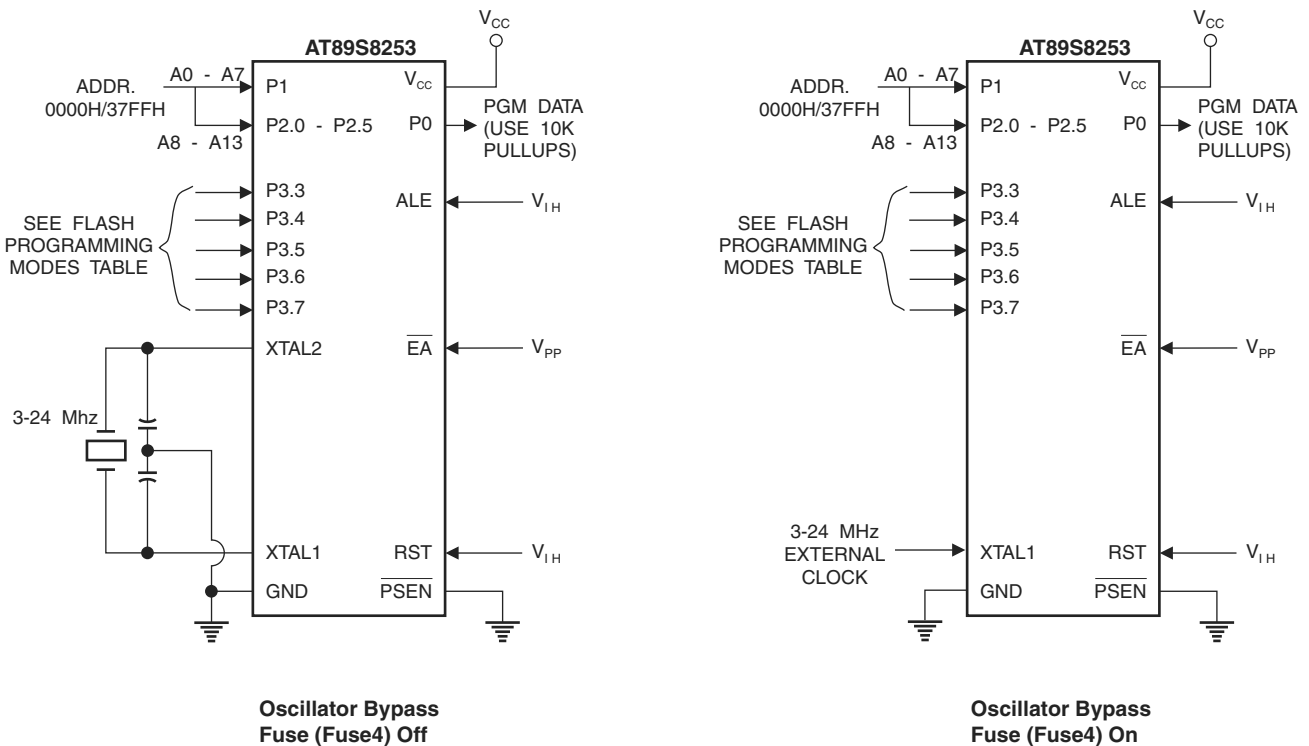
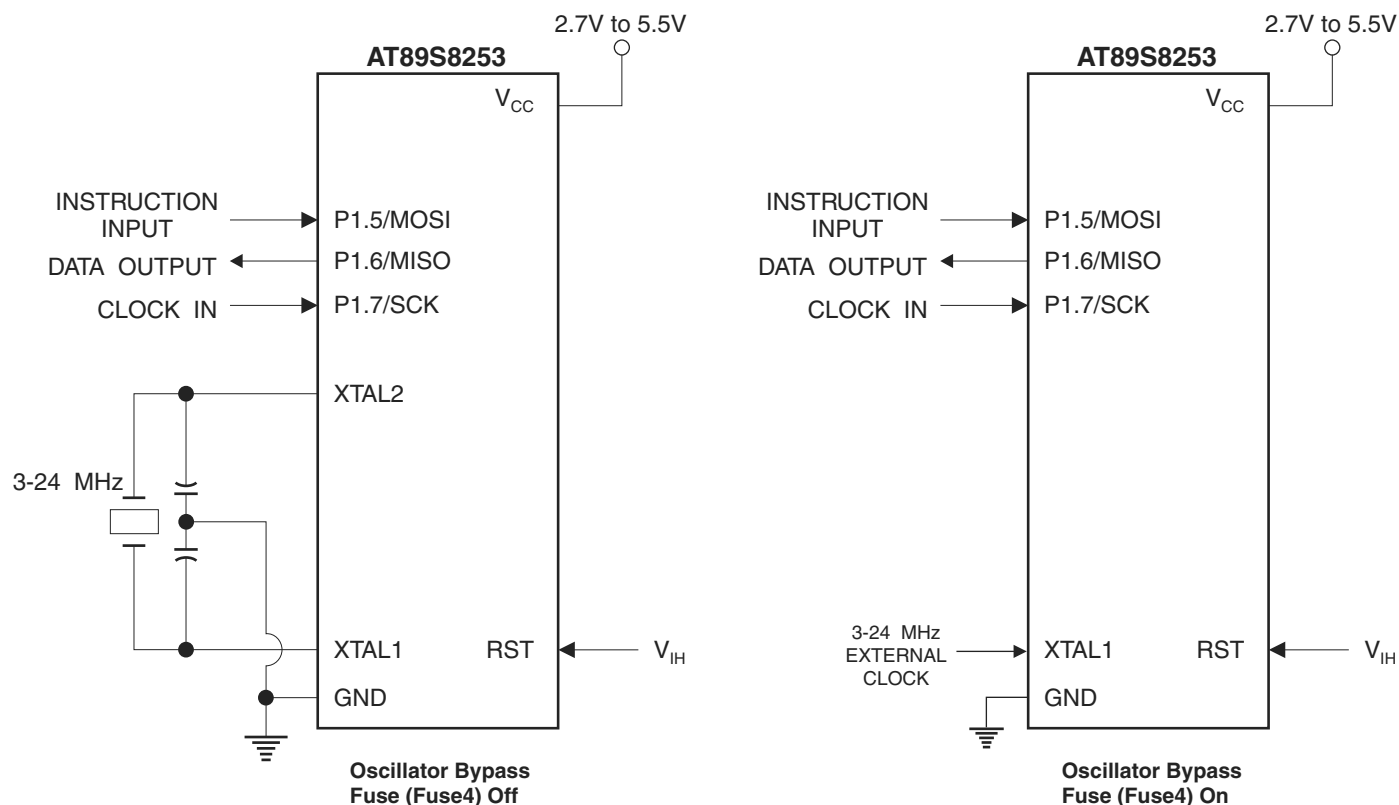
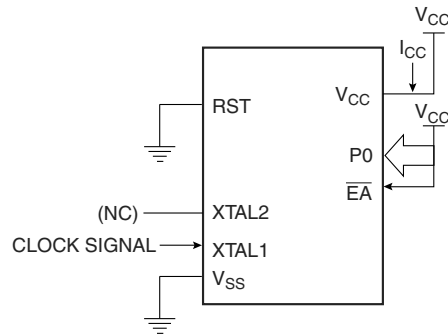


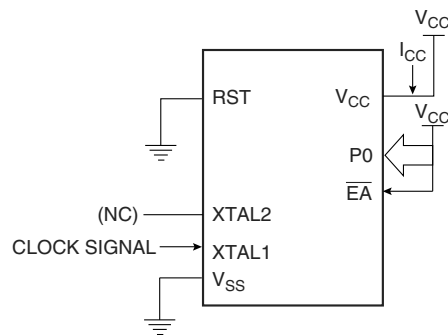
Figure 25-3. Flash/EEPROM Serial Downloading



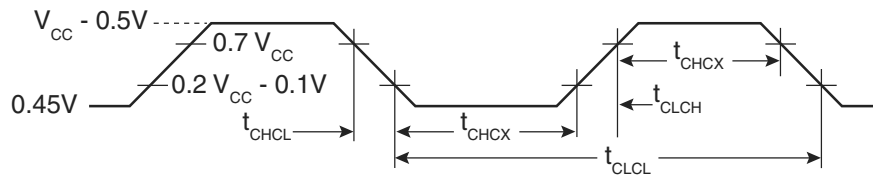
41. I_{CC} Test Condition, Active Mode, All Other Pins are Disconnected



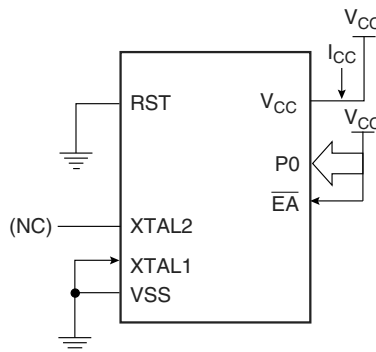
42. I_{CC} Test Condition, Idle Mode, All Other Pins are Disconnected



43. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes, $t_{CLCH} = t_{CHCL} = 5 \text{ ns}$



44. I_{CC} Test Condition, Power-down Mode, All Other Pins are Disconnected, $V_{CC} = 2V \text{ to } 5.5V$



48. Ordering Information

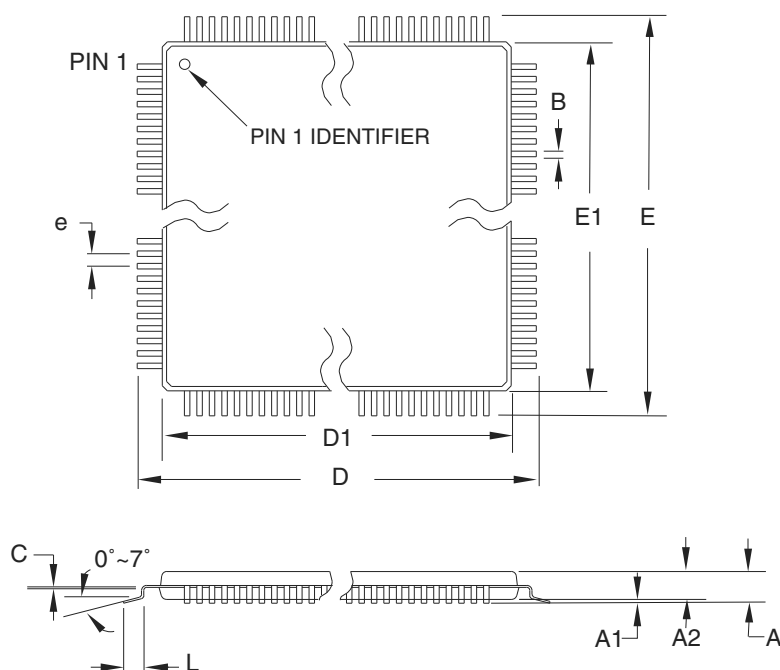
48.1 Green Package (Pb/Halide-free)

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
24	2.7V to 5.5V	AT89S8253-24AU AT89S8253-24JU AT89S8253-24PU AT89S8253-24PSU	44A 44J 40P6 42PS6	Industrial (-40° C to 85° C)

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flat Package (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
40P6	40-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
42PS6	42-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)

49. Package Information

49.1 44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

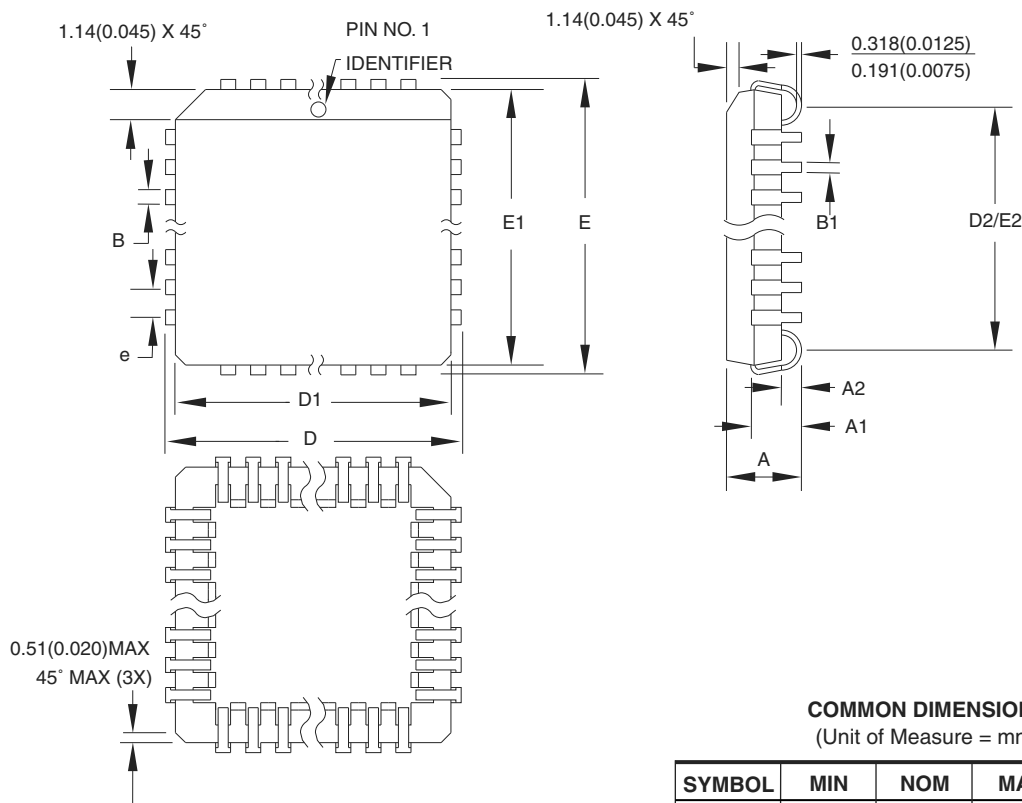
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
 3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

2325 Orchard Parkway San Jose, CA 95131	TITLE	DRAWING NO.	REV.
	44A , 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

49.2 44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010" (0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

2325 Orchard Parkway
San Jose, CA 95131

TITLE

44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)

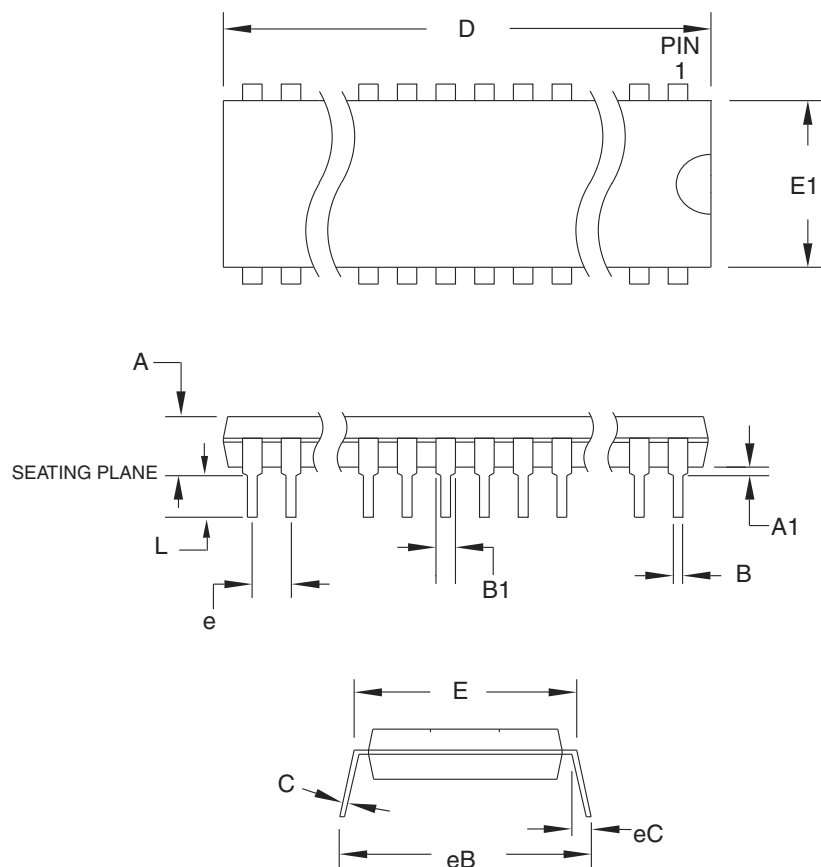
DRAWING NO.

44J

REV.

B

49.4 42PS6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = Inch)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	0.200	
A1	0.020	–	–	
D	1.440	1.450	1.460	Note 2
E	0.600	–	0.630	
E1	0.500	0.540	0.570	Note 2
B	0.015	0.018	0.022	
B1	0.035	0.040	0.045	
L	0.100	0.130	0.140	
C	0.009	0.010	0.015	
eB	–	–	0.730	
eC	0.000	–	0.060	
e	0.70 TYP			

Notes: 1. This package conforms to JEDEC reference MS-020, Variation AB.
2. Dimensions D and E1 do not include mold Flash or Protrusion.
Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

11/3/06



2325 Orchard Parkway
San Jose, CA 95131

TITLE

42PS6, 42-lead (Shrink 0.070"/0.600" Row Space)
Plastic Dual Inline Package (PDIP)

DRAWING NO.

42PS6

REV.

B





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